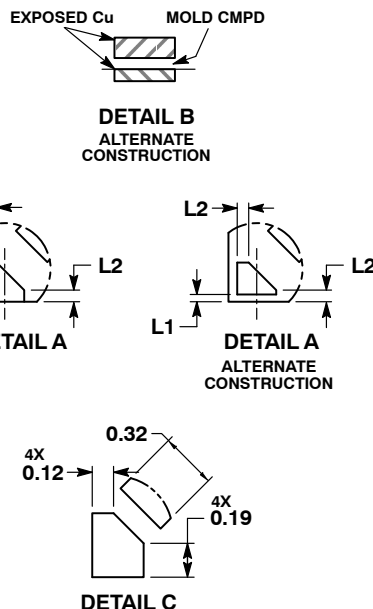
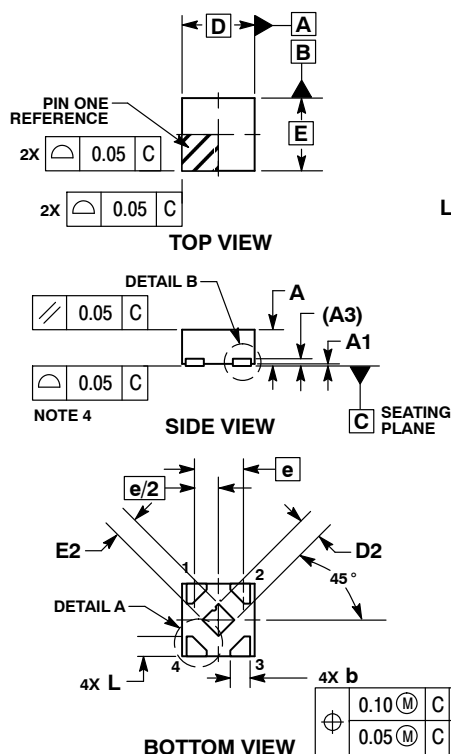




SCALE 4:1

XDFN4 0.8x0.8, 0.48P
CASE 711BF
ISSUE 0

DATE 26 FEB 2016



NOTES:

1. DIMENSIONING AND TOLERANCING PER ASME Y14.5M, 1994.
2. CONTROLLING DIMENSION: MILLIMETERS.
3. DIMENSION b APPLIES TO PLATED TERMINALS.
4. COPLANARITY APPLIES TO THE EXPOSED PAD AS WELL AS THE TERMINALS.

	MILLIMETERS	
DIM	MIN	MAX
A	0.33	0.43
A1	0.00	0.05
A3	0.127 REF	
b	0.17	0.27
D	0.80 BSC	
D2	0.20	0.30
E	0.80 BSC	
E2	0.20	0.30
e	0.48 BSC	
L	0.17	0.27
L1		0.10
L2	0.06 REF	

GENERIC MARKING DIAGRAM*

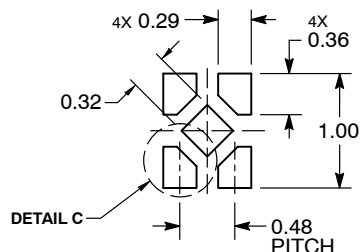


XX = Specific Device Code
M = Date Code

*This information is generic. Please refer to device data sheet for actual part marking.

Pb-Free indicator, "G" or microdot "■", may or may not be present.

RECOMMENDED MOUNTING FOOTPRINT*



DIMENSIONS: MILLIMETERS

*For additional information on our Pb-Free strategy and soldering details, please download the **onsemi** Soldering and Mounting Techniques Reference Manual, [SOLDERM/D](#).

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DESCRIPTION:	XDFN4 0.8X0.8, 0.48P	PAGE 1 OF 1

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